



7P20

Power MOSFET

200V P-CHANNEL MOSFET

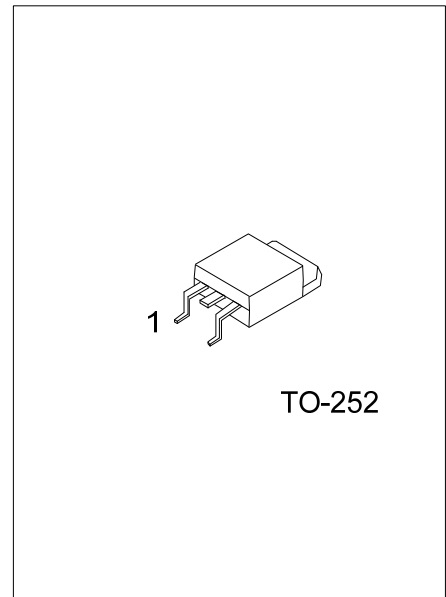
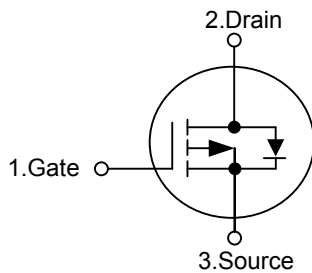
DESCRIPTION

The **7P20** uses advanced proprietary, planar stripe, DMOS technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications. They are also well suited for high efficiency switching DC/DC converters.

FEATURES

- * $R_{DS(ON)} \cong 0.69\Omega @ V_{GS} = -10V$
- * Ultra Low Gate Charge (typical 19 nC)
- * Low Reverse Transfer Capacitance ($C_{RSS} = \text{Typical } 25 \text{ pF}$)
- * Fast Switching Capability
- * Avalanche Energy Specified
- * Improved dv/dt Capability, High Ruggedness

SYMBOL



ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
7P20L-TN3-R	7P20G-TN3-R	TO-252	G	D	S	Tape Reel

<p>7P20G-TN3-R</p> <p>(1)Packing Type</p> <p>(2)Package Type</p> <p>(3)Halogen Free</p>	<p>(1) R: Tape Reel</p> <p>(2) TN3: TO-252</p> <p>(3) G: Halogen Free, L: Lead Free</p>
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■ ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	V_{DSS}	-200	V
Gate-Source Voltage	V_{GSS}	± 30	V
Continuous Drain Current	I_D	-5.7	A
Pulsed Drain Current (Note 2)	I_{DM}	-22.8	A
Avalanche Current (Note 2)	I_{AR}	-5.7	A
Single Pulsed Avalanche Energy (Note 3)	E_{AS}	570	mJ
Repetitive Avalanche Energy (Note 2)	E_{AR}	5.5	mJ
Peak Diode Recovery dv/dt (Note 4)	dv/dt	-5.5	V/ns
Power Dissipation	P_D	$T_a = 25^\circ\text{C}$	2.5
		$T_C = 25^\circ\text{C}$	55
Junction Temperature	T_J	+150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 ~ +150	$^\circ\text{C}$

Note: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- Pulse width limited by $T_{J(MAX)}$
- $L=26.3\text{mH}$, $I_{AS}=-5.7\text{A}$, $V_{DD}=-50\text{V}$, $R_G=25\Omega$
- $I_{SD} \leq -7.3\text{A}$, $di/dt \leq 300\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	100	$^\circ\text{C}/\text{W}$
Junction to Case	θ_{JC}	2.27	$^\circ\text{C}/\text{W}$

■ ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-200			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D=-250\mu\text{A}$, Referenced to 25°C		-0.1		$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=-200\text{V}$, $V_{GS}=0\text{V}$			-1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0\text{V}$, $V_{GS}=\pm 30\text{V}$			± 100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-2.0		-4.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10\text{V}$, $I_D=-2.85\text{A}$		0.54	0.69	Ω
Forward Transconductance	g_{FS}	$V_{DS}=-40\text{V}$, $I_D=-2.85\text{A}$ (Note 1)		3.7		S
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{DS}=-25\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$		590	770	pF
Output Capacitance	C_{OSS}		140	180	pF	
Reverse Transfer Capacitance	C_{RSS}		25	35	pF	
SWITCHING PARAMETERS						
Total Gate Charge	Q_G	$V_{DS}=-160\text{V}$, $V_{GS}=-10\text{V}$, $I_D=-7.3\text{A}$ (Note 1, 2)		19	25	nC
Gate Source Charge	Q_{GS}		4.6		nC	
Gate Drain Charge	Q_{GD}		9.5		nC	
Turn-ON Delay Time	$t_{D(ON)}$	$V_{DD}=-100\text{V}$, $I_D=-7.3\text{A}$, $R_G=25\Omega$ (Note 1, 2)		15	40	ns
Turn-ON Rise Time	t_R		110	230	ns	
Turn-OFF Delay Time	$t_{D(OFF)}$		30	70	ns	
Turn-OFF Fall-Time	t_F		42	90	ns	
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Diode Forward Voltage	V_{SD}	$I_S=-5.7\text{A}$, $V_{GS}=0\text{V}$			-5.0	V
Maximum Body-Diode Continuous Current	I_S				-5.7	A
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}				-22.8	A
Body Diode Reverse Recovery Time	t_{RR}	$V_{GS}=0\text{V}$, $I_S=-7.30\text{A}$		180		ns
Body Diode Reverse Recovery Charge	Q_{RR}	$di_F/dt=100\text{A/s}$ (Note 1)		1.07		μC

Note: 1. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

2. Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS

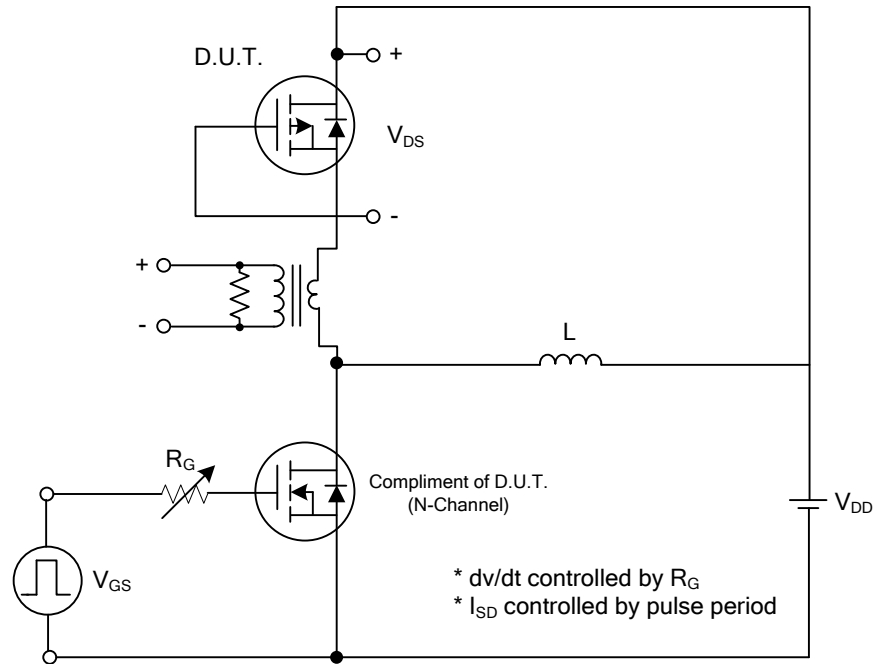


Fig. 1A Peak Diode Recovery dv/dt Test Circuit

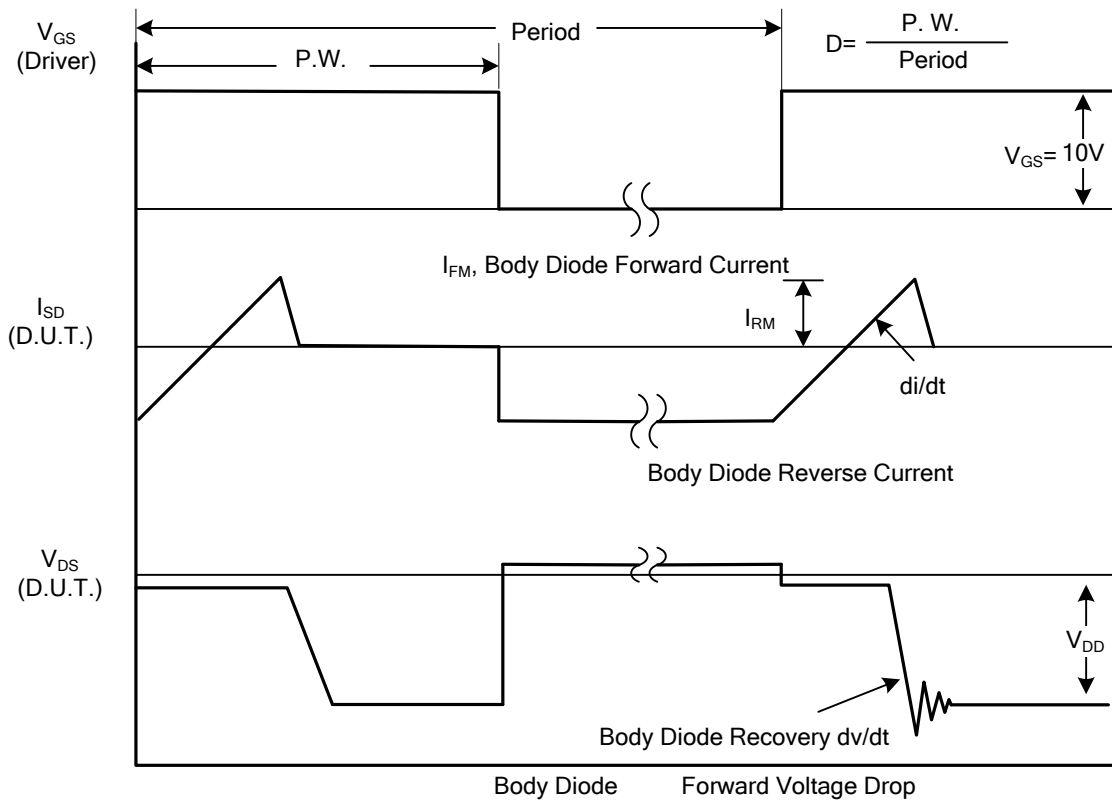


Fig. 1B Peak Diode Recovery dv/dt Waveforms

■ TEST CIRCUITS AND WAVEFORMS (Cont.)

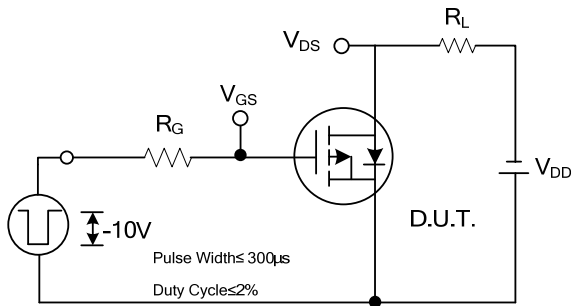


Fig. 2A Switching Test Circuit

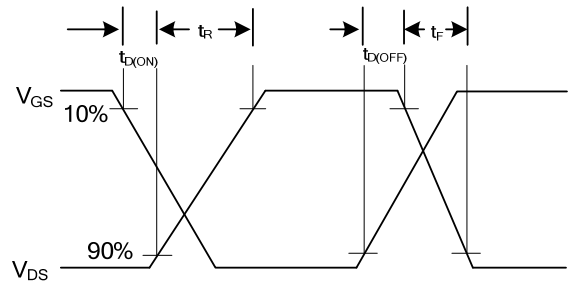


Fig. 2B Switching Waveforms

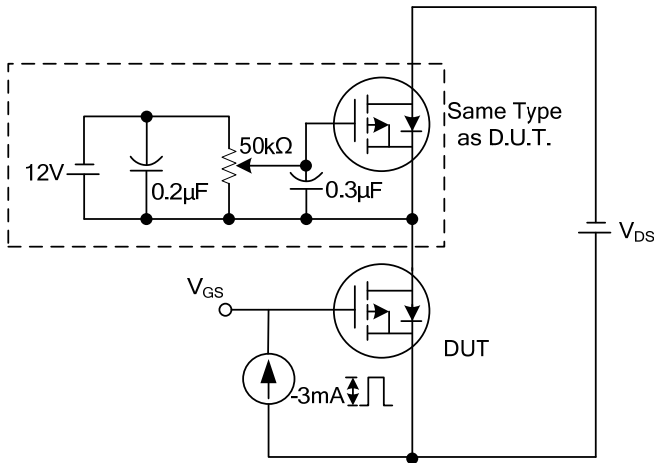


Fig. 3A Gate Charge Test Circuit

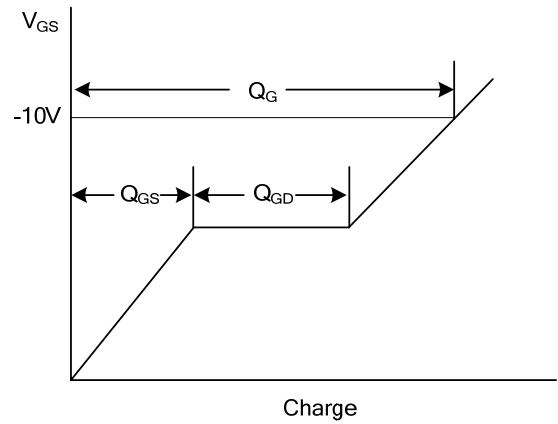


Fig. 3B Gate Charge Waveform

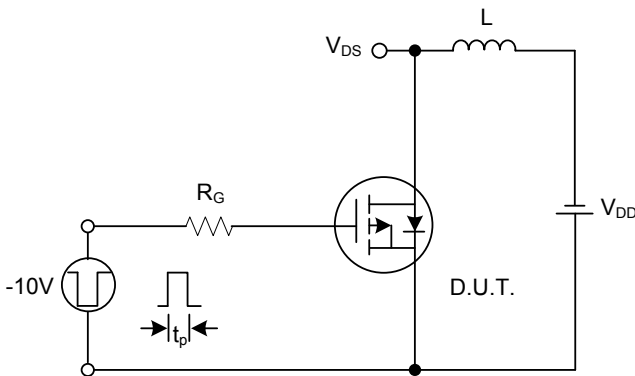


Fig. 4A Unclamped Inductive Switching Test Circuit

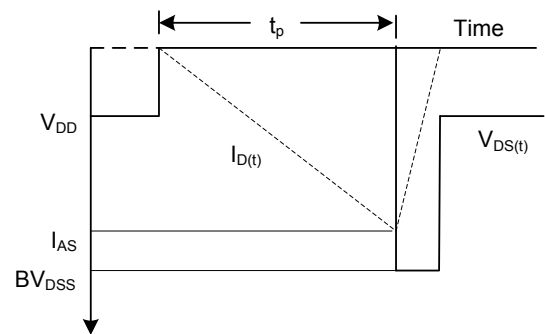
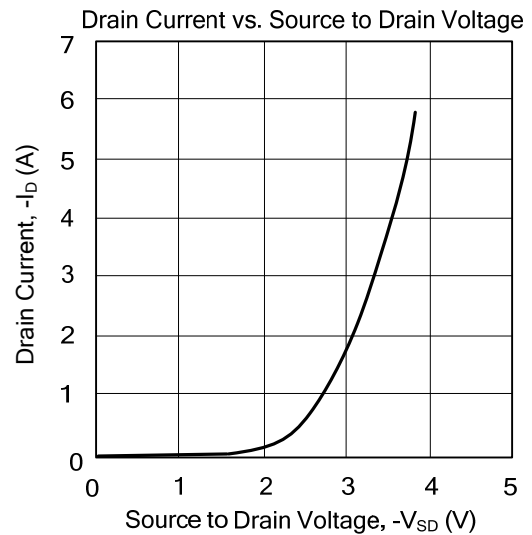
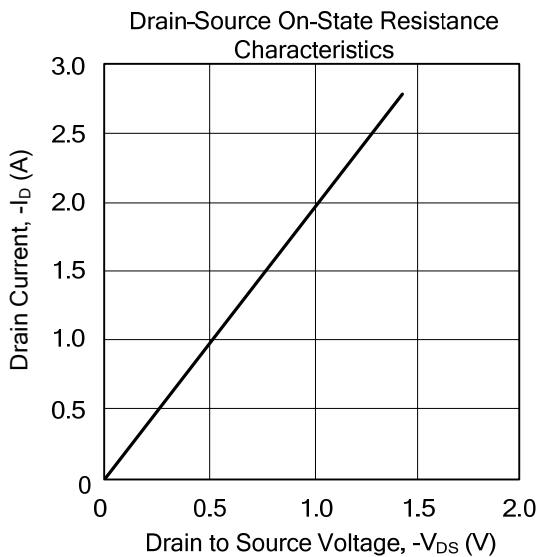
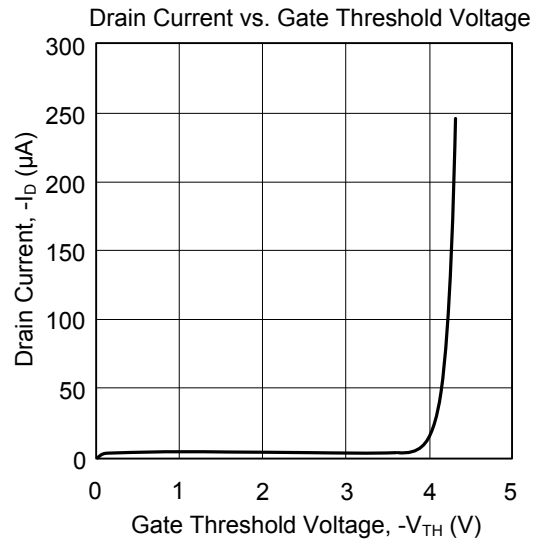
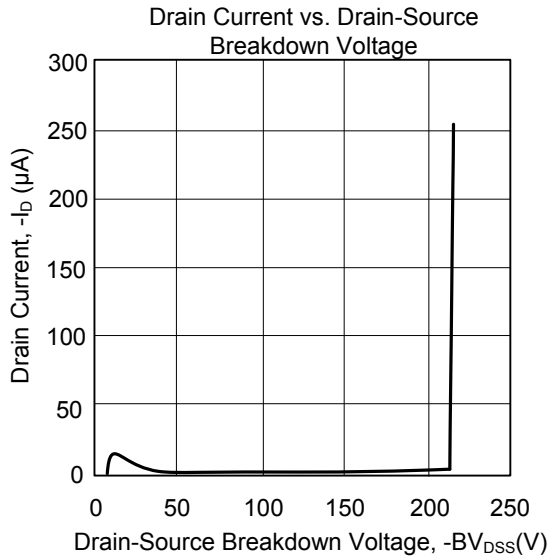


Fig. 4B Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS



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